

Thermal transfer compounds

Silicon thermal transfer compound

– thermal transfer compound used to reduce the thermal transmission resistance between semiconductor and heatsink



art. no.	basin	delivery quantity [g]
WLP 004	box	4
WLP 035	box	35
WLP 500	box	500
WLP 300 S	cartridge (310 ml)	300
WLP 500 S	cartridge (310 ml)	500

Silicone-free thermal transfer compound

– thermal transfer compound used to reduce the thermal transmission resistance between semiconductor and heatsink



art. no.	basin	delivery quantity [ml]	delivery quantity [g]
WLPF 05	syringe	2	—
WLPF 10	syringe	5	—
WLPF 20	syringe	10	—
WLPF 50	syringe	20	—
WLPF 300 S	cartridge (310 ml)	—	300

	WLP	WLPF
composition	silicone oil, inorganic filling material	silicone free synthetic liquid. Metal oxide filling.
consistance	pasty	
colour	white	white-grey
tightness	1.1 g/cm ³	ca. 2 g/cm ³
thermal conductivity	0.61 W/m·K	>0.7 W/m·K
specific electrical resistance	>10 ¹² Ω/cm	
flashpoint	none (DIN 53213)	of the basic oil >280 °C (ISO 2592)
drop point	>260 °C	
thermal resistance	no bleeding at (4 h / 200°C)	<1 % (96 h / 200 °C)
temperature range	-70 °C ... +250 °C	-40 °C ... +150 °C
acid number	< 0.01 mg KOH/g	
solubility in water	insoluble	

Thermal transfer compounds

Ceramic filled, silicone-free thermal conductive paste with high thermal conductivity

- suitable especially for silicone-sensitive applications
- no drying out, hardening or melting of the thermal conductive paste
- high long-term stability
- further package sizes, container types such as cans, cartridge, etc. upon request



art. no.	basin	delivery quantity [ml]
WLPK 3	syringe	3
WLPK 5	syringe	5
WLPK 10	syringe	10

	WLPK
composition	silicone-free, synthetic fluid ceramic filled
consistance	pastey
colour	silver
tightness	1.4 g/cm ³
thermal conductivity	10 W/m·K
dielectric strength	not applicable, because conducting
temperature range	-60 °C ... +150 °C
solubility in water	insoluble

Thermally conductive adhesive

- thermally conductive, electrically non-conductive adhesive
- two part epoxy resin adhesive, metaloxide filled
- fully replaces mechanical fastenings
- excellent function and application characteristics
- to be stored at a cool and dark place

WLK 5		WLK 10	
art. no.	composition	art. no.	composition
WLK 5	5 g resin / 0.5 g hardener	WLK 10	10 g resin / 1 g hardener
WLK 30		WLK 120	
art. no.	composition	art. no.	composition
WLK 30	30 g resin / 3 g hardener	WLK 120	120 g resin / 12 g hardener
		WLK	
thermal conductivity	0.836 W/m·K		
pass resistance	$10^{16} \Omega/\text{cm}$		
specific thermal resistance	1.2 m·K/W		
temperature range	-56 °C ... +149 °C		
hardening time	20 °C approx. 16 - 24 h/ 190 °C approx. 20 min/ 38 °C approx. 6 h		
glue layer	Epoxid		
mixture proportion	10:1		

Thermally conductive adhesive

- solvent-free and thermal conductive two part adhesive
- epoxy based filled with aluminium oxide
- composition of hardener and resin (1:1) with statical mixing tube
- lockability of the container via Luer-Lock System
- good usage and working properties

WLK DK 4	WLK DK 10	WLK DK 50
		
art. no.	basin	contents of delivery
WLK DK 4	syringe	1x 4 ml syringe / 3x mixer WLK M 4
WLK DK 10	syringe	1x 10 ml syringe / 3x mixer WLK M 4
WLK DK 50	cartridge	1x 50 ml cartridge / 3x mixer WLK M 50

	WLK DK
thermal conductivity	1.0 W/m·K
pass resistance	8x10 ¹¹ Ω/cm
specific thermal resistance	118°C cm/W
temperature range	-50 °C ... +145 °C
working life at room temperature	approx. 30 min
hardening time	25 °C ca. 4 h / 50 °C ca. 1 h / 85 °C ca. 10 min / 125 °C ca. 2 min
glue layer	Epoxid
mixture proportion	1:1

Accessories

- more package sizes and container types upon request
- store cool and dry

art. no.	contents of delivery
WLK M 4	10x mixer für 4 & 10 ml syringe (packing unit 10 pieces)
WLK M 50	10x mixer für 50 ml cartridge (packing unit 10 pieces)
WLK P	1x applicator gun for 50 ml cartridge